ABSTRACT

An integrated circuit including a copper interconnection layer includes an aluminum distribution layer overlying the copper interconnection layer to distribute external electrical signals such as power, ground, and clock signals throughout the die of the device. The distribution layer overlies the copper interconnection layer in a grid pattern which connects to the copper interconnection layer through a plurality of vias. The distribution layer further includes a plurality of wire bond pads to permit wire bonding between the distribution layer and bonding pads of the integrated circuit package.